

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±12	V
Drain Current (Note 5)	Steady State	T _A = +25°C	I _D	7.63	A
		T _A = +85°C		4.92	
Pulsed Drain Current (Note 6)			I _{DM}	30	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P _D	1.16	W
Thermal Resistance, Junction to Ambient @T _A = +25°C	R _{θJA}	107.4	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	—	—	1	μA	V _{DS} = 20V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±12V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(th)}	0.5	—	1.2	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(on)}	—	19	28	mΩ	V _{GS} = 4.5V, I _D = 6A
			25	41		V _{GS} = 2.5V, I _D = 5.2A
Forward Transfer Admittance	Y _{fs}	—	6	—	S	V _{DS} = 10V, I _D = 6A
Diode Forward Voltage	V _{SD}	—	0.7	1.2	V	V _{GS} = 0V, I _S = 1.7A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	—	550	—	pF	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz
Output Capacitance	C _{oss}	—	88	—		
Reverse Transfer Capacitance	C _{rss}	—	81	—		
Gate Resistance	R _g	—	1.34	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge	Q _g	—	15.6	—	nC	V _{GS} = 10V, V _{DS} = 10V, I _D = 6A
Total Gate Charge	Q _g	—	7.2	—		
Gate-Source Charge	Q _{gs}	—	1	—	nC	V _{GS} = 4.5 V, V _{DS} = 10V, I _D = 6A
Gate-Drain Charge	Q _{gd}	—	1.9	—		
Turn-On Delay Time	t _{D(on)}	—	4.69	—	ns	V _{DD} = 10V, V _{GEN} = 4.5V, R _g = 1Ω, I _D = 6.7A
Turn-On Rise Time	t _r	—	13.19	—		
Turn-Off Delay Time	t _{D(off)}	—	22.1	—		
Turn-Off Fall Time	t _f	—	6.43	—		

- Notes:
- Device mounted on FR-4 PCB with minimum recommended pad layout.
 - Repetitive rating, pulse width limited by function temperature.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to production testing.

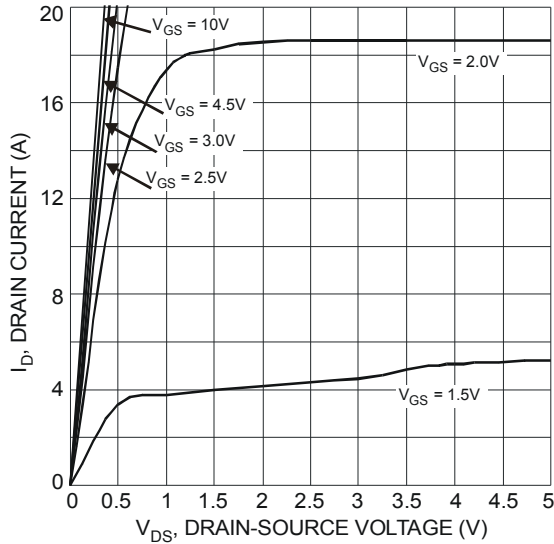


Fig. 1 Typical Output Characteristics

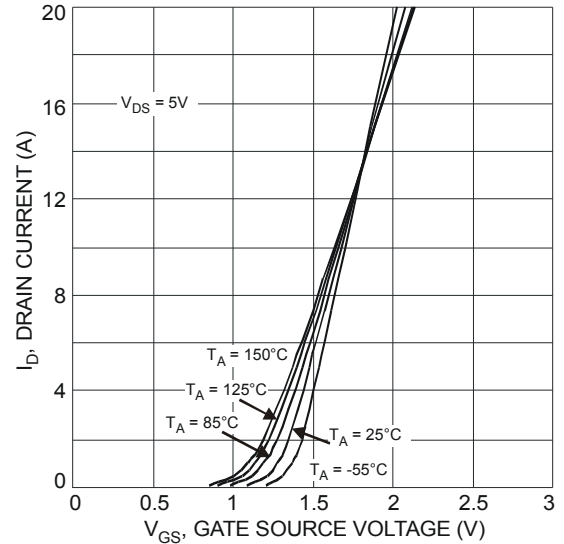


Fig. 2 Typical Transfer Characteristics

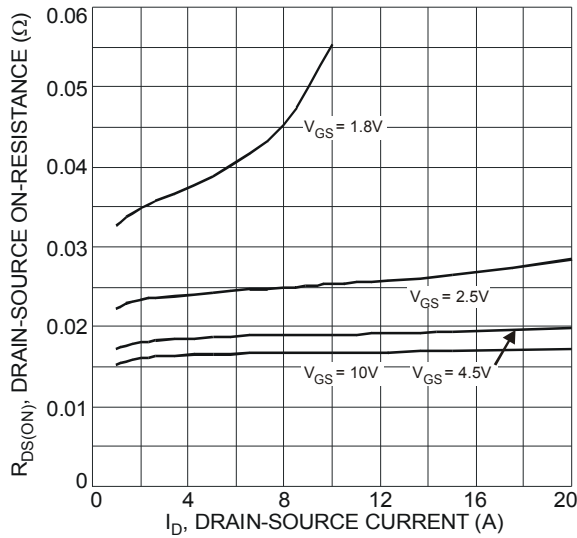


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

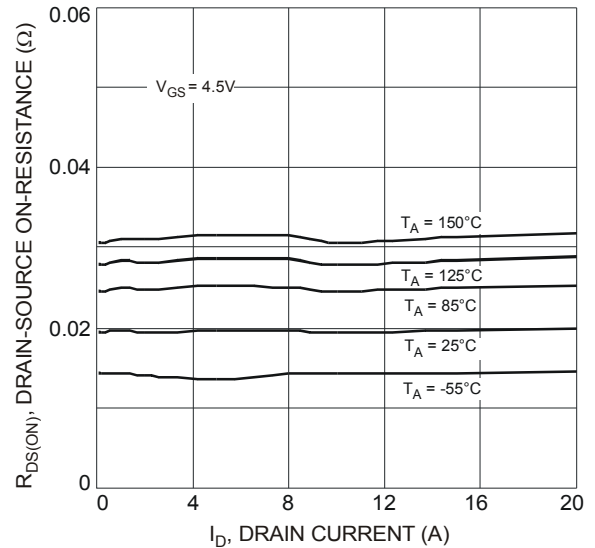


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

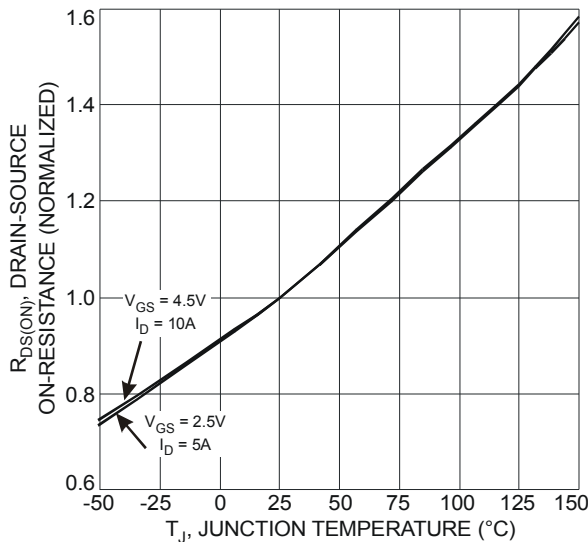


Fig. 5 On-Resistance Variation with Temperature

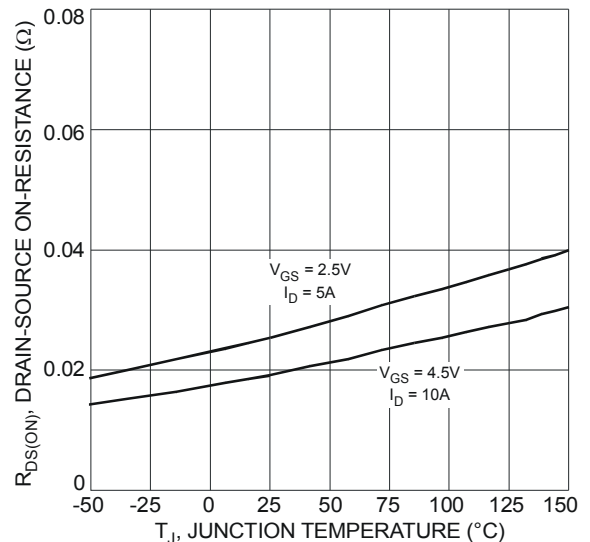


Fig. 6 On-Resistance Variation with Temperature

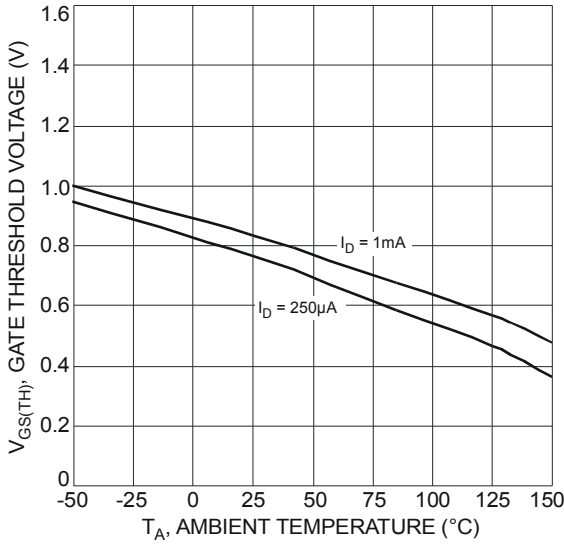


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

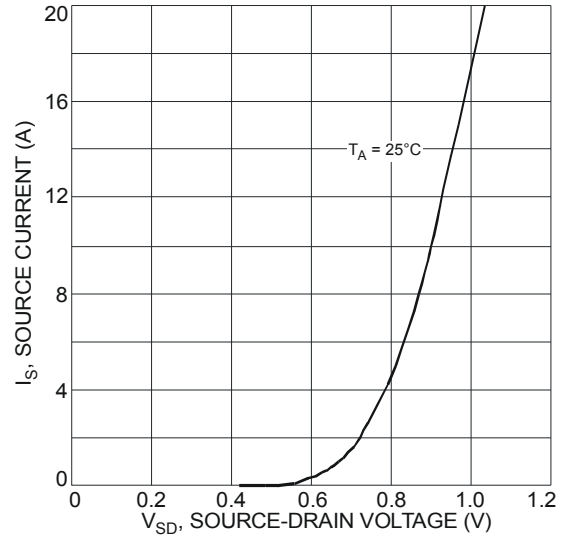


Fig. 8 Diode Forward Voltage vs. Current

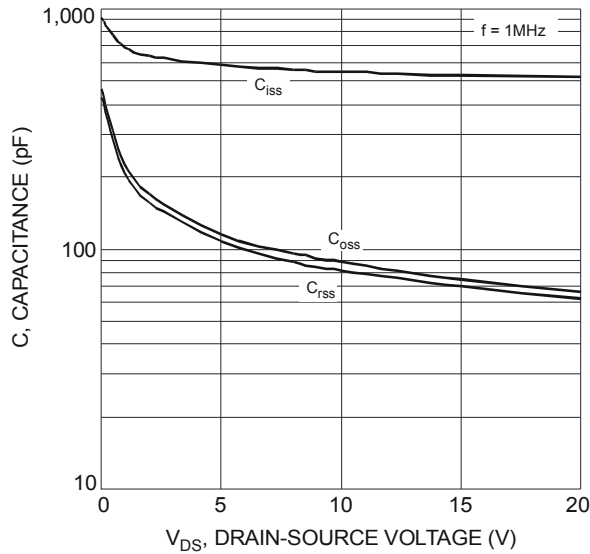


Fig. 9 Typical Capacitance

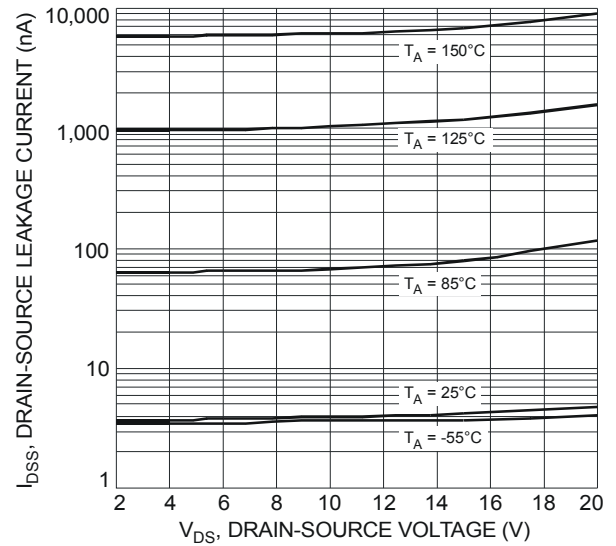


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

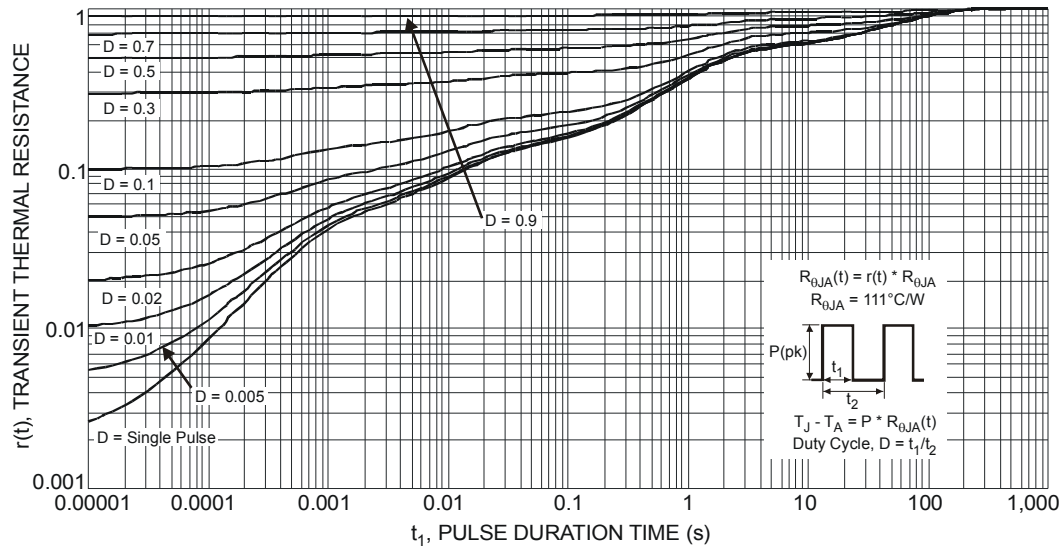
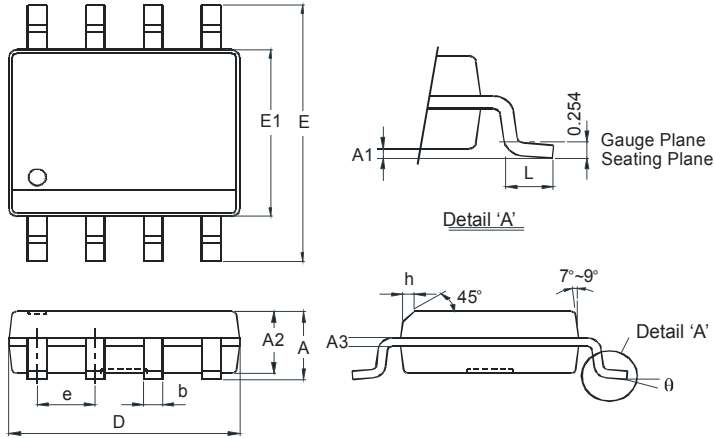


Fig. 11 Transient Thermal Response

Package Outline Dimensions

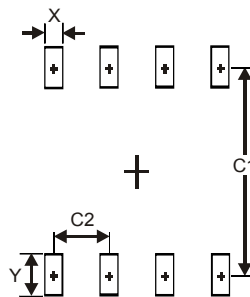
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	-	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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